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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

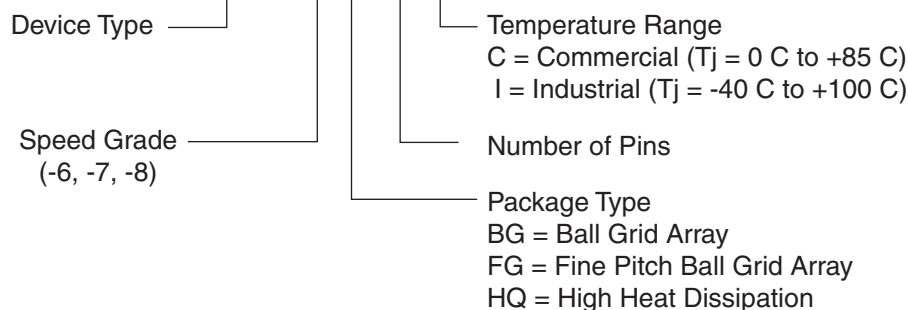
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1536
Number of Logic Elements/Cells	6912
Total RAM Bits	131072
Number of I/O	176
Number of Gates	411955
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv300e-7fg256i

Virtex-E Ordering Information

Example: XCV300E-6PQ240C



DS022_043_072000

Figure 1: Ordering Information

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T _{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V _{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	- Numerous minor edits. - Data sheet upgraded to Preliminary. - Preview -8 numbers added to Virtex-E Electrical Characteristics tables.
8/1/00	1.6	- Reformatted entire document to follow new style guidelines. - Changed speed grade values in tables on pages 35-37.
9/20/00	1.7	- Min values added to Virtex-E Electrical Characteristics tables. - XCV2600E and XCV3200E numbers added to Virtex-E Electrical Characteristics tables (Module 3). - Corrected user I/O count for XCV100E device in Table 1 (Module 1). - Changed several pins to "No Connect in the XCV100E" and removed duplicate V_{CCINT} pins in Table ~ (Module 4). - Changed pin J10 to "No connect in XCV600E" in Table 74 (Module 4). - Changed pin J30 to "VREF option only in the XCV600E" in Table 74 (Module 4). - Corrected pair 18 in Table 75 (Module 4) to be "AO in the XCV1000E, XCV1600E".

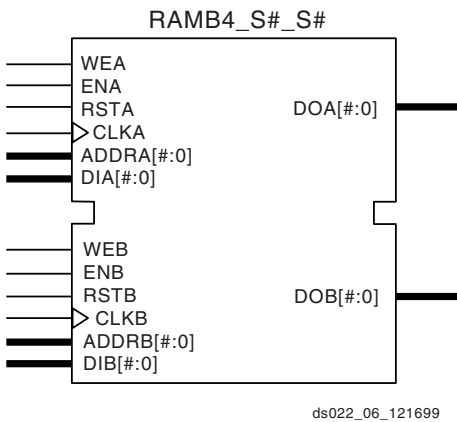


Figure 6: Dual-Port Block SelectRAM

Table 5 shows the depth and width aspect ratios for the block SelectRAM. The Virtex-E block SelectRAM also includes dedicated routing to provide an efficient interface with both CLBs and other block SelectRAMs. Refer to XAPP130 for block SelectRAM timing waveforms.

Table 5: Block SelectRAM Port Aspect Ratios

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

Programmable Routing Matrix

It is the longest delay path that limits the speed of any worst-case design. Consequently, the Virtex-E routing architecture and its place-and-route software were defined in a joint optimization process. This joint optimization minimizes long-path delays, and consequently, yields the best system performance.

The joint optimization also reduces design compilation times because the architecture is software-friendly. Design cycles are correspondingly reduced due to shorter design iteration times.

Local Routing

The VersaBlock provides local routing resources (see Figure 7), providing three types of connections:

- Interconnections among the LUTs, flip-flops, and GRM
- Internal CLB feedback paths that provide high-speed connections to LUTs within the same CLB, chaining them together with minimal routing delay

- Direct paths that provide high-speed connections between horizontally adjacent CLBs, eliminating the delay of the GRM.

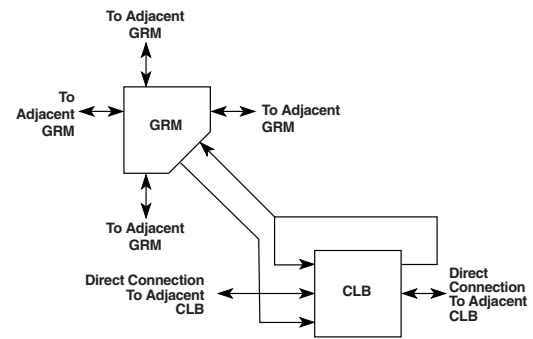


Figure 7: Virtex-E Local Routing

General Purpose Routing

Most Virtex-E signals are routed on the general purpose routing, and consequently, the majority of interconnect resources are associated with this level of the routing hierarchy. General-purpose routing resources are located in horizontal and vertical routing channels associated with the CLB rows and columns and are as follows:

- Adjacent to each CLB is a General Routing Matrix (GRM). The GRM is the switch matrix through which horizontal and vertical routing resources connect, and is also the means by which the CLB gains access to the general purpose routing.
- 24 single-length lines route GRM signals to adjacent GRMs in each of the four directions.
- 72 buffered Hex lines route GRM signals to another GRMs six-blocks away in each one of the four directions. Organized in a staggered pattern, Hex lines are driven only at their endpoints. Hex-line signals can be accessed either at the endpoints or at the midpoint (three blocks from the source). One third of the Hex lines are bidirectional, while the remaining ones are uni-directional.
- 12 Longlines are buffered, bidirectional wires that distribute signals across the device quickly and efficiently. Vertical Longlines span the full height of the device, and horizontal ones span the full width of the device.

I/O Routing

Virtex-E devices have additional routing resources around their periphery that form an interface between the CLB array and the IOBs. This additional routing, called the VersaRing, facilitates pin-swapping and pin-locking, such that logic redesigns can adapt to existing PCB layouts. Time-to-market is reduced, since PCBs and other system components can be manufactured while the logic design is still in progress.

Data Registers

The primary data register is the Boundary Scan register. For each IOB pin in the FPGA, bonded or not, it includes three bits for In, Out, and 3-State Control. Non-IOB pins have appropriate partial bit population if input-only or output-only. Each EXTEST CAPTURED-OR state captures all In, Out, and 3-state pins.

The other standard data register is the single flip-flop BYPASS register. It synchronizes data being passed through the FPGA to the next downstream Boundary Scan device.

The FPGA supports up to two additional internal scan chains that can be specified using the BSCAN macro. The macro provides two user pins (SEL1 and SEL2) which are decodes of the USER1 and USER2 instructions respectively. For these instructions, two corresponding pins (TDO1 and TDO2) allow user scan data to be shifted out of TDO.

Likewise, there are individual clock pins (DRCK1 and DRCK2) for each user register. There is a common input pin (TDI) and shared output pins that represent the state of the TAP controller (RESET, SHIFT, and UPDATE).

Bit Sequence

The order within each IOB is: In, Out, 3-State. The input-only pins contribute only the In bit to the Boundary Scan I/O data register, while the output-only pins contribute all three bits.

From a cavity-up view of the chip (as shown in EPIC), starting in the upper right chip corner, the Boundary Scan data-register bits are ordered as shown in [Figure 12](#).

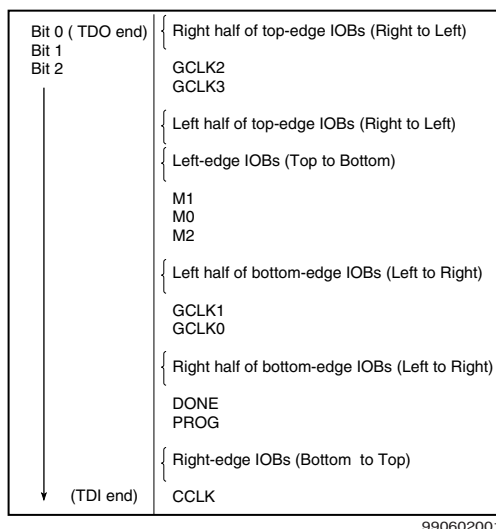


Figure 12: Boundary Scan Bit Sequence

BSDL (Boundary Scan Description Language) files for Virtex-E Series devices are available on the Xilinx web site in the File Download area.

Identification Registers

The IDCODE register is supported. By using the IDCODE, the device connected to the JTAG port can be determined.

The IDCODE register has the following binary format:

vvvv:ffff:ffa:aaaa:aaaa:cccc:cccc:ccc1

where

v = the die version number

f = the family code (05 for Virtex-E family)

a = the number of CLB rows (ranges from 16 for XCV50E to 104 for XCV3200E)

c = the company code (49h for Xilinx)

The USERCODE register is supported. By using the USERCODE, a user-programmable identification code can be loaded and shifted out for examination. The identification code (see [Table 7](#)) is embedded in the bitstream during bitstream generation and is valid only after configuration.

Table 7: IDCODEs Assigned to Virtex-E FPGAs

FPGA	IDCODE
XCV50E	v0A10093h
XCV100E	v0A14093h
XCV200E	v0A1C093h
XCV300E	v0A20093h
XCV400E	v0A28093h
XCV600E	v0A30093h
XCV1000E	v0A40093h
XCV1600E	v0A48093h
XCV2000E	v0A50093h
XCV2600E	v0A5C093h
XCV3200E	v0A68093h

Note:

Attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Including Boundary Scan in a Design

Since the Boundary Scan pins are dedicated, no special element needs to be added to the design unless an internal data register (USER1 or USER2) is desired.

If an internal data register is used, insert the Boundary Scan symbol and connect the necessary pins as appropriate.

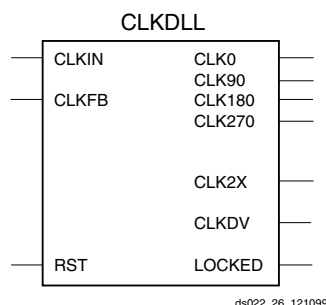


Figure 22: Standard DLL Symbol CLKDLL

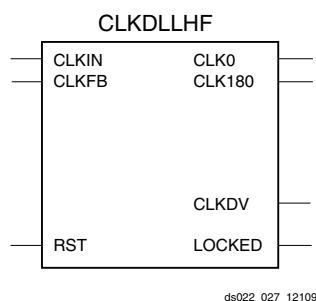


Figure 23: High Frequency DLL Symbol CLKDLLHF

BUFGDLL Pin Descriptions

Use the BUFGDLL macro as the simplest way to provide zero propagation delay for a high-fanout on-chip clock from an external input. This macro uses the IBUFG, CLKDLL and BUFG primitives to implement the most basic DLL application as shown in Figure 24.

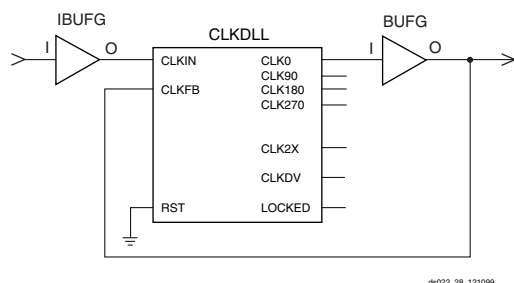


Figure 24: BUFGDLL Schematic

This symbol does not provide access to the advanced clock domain controls or to the clock multiplication or clock division features of the DLL. This symbol also does not provide access to the RST, or LOCKED pins of the DLL. For access to these features, a designer must use the library DLL primitives described in the following sections.

Source Clock Input — I

The I pin provides the user source clock, the clock signal on which the DLL operates, to the BUFGDLL. For the BUFGDLL macro the source clock frequency must fall in the low frequency range as specified in the data sheet. The BUF-

GDLL requires an external signal source clock. Therefore, only an external input port can source the signal that drives the BUFGDLL I pin.

Clock Output — O

The clock output pin O represents a delay-compensated version of the source clock (I) signal. This signal, sourced by a global clock buffer BUFG symbol, takes advantage of the dedicated global clock routing resources of the device.

The output clock has a 50-50 duty cycle unless you deactivate the duty cycle correction property.

CLKDLL Primitive Pin Descriptions

The library CLKDLL primitives provide access to the complete set of DLL features needed when implementing more complex applications with the DLL.

Source Clock Input — CLKIN

The CLKIN pin provides the user source clock (the clock signal on which the DLL operates) to the DLL. The CLKIN frequency must fall in the ranges specified in the data sheet. A global clock buffer (BUFG) driven from another CLKDLL, one of the global clock input buffers (IBUFG), or an IO_LVDS_DLL pin on the same edge of the device (top or bottom) must source this clock signal. There are four IO_LVDS_DLL input pins that can be used as inputs to the DLLs. This makes a total of eight usable input pins for DLLs in the Virtex-E family.

Feedback Clock Input — CLKFB

The DLL requires a reference or feedback signal to provide the delay-compensated output. Connect only the CLK0 or CLK2X DLL outputs to the feedback clock input (CLKFB) pin to provide the necessary feedback to the DLL. The feedback clock input can also be provided through one of the following pins.

IBUFG - Global Clock Input Pad

IO_LVDS_DLL - the pin adjacent to IBUFG

If an IBUFG sources the CLKFB pin, the following special rules apply.

1. An external input port must source the signal that drives the IBUFG I pin.
2. The CLK2X output must feedback to the device if both the CLK0 and CLK2X outputs are driving off chip devices.
3. That signal must directly drive only OBUFs and nothing else.

These rules enable the software determine which DLL clock output sources the CLKFB pin.

Reset Input — RST

When the reset pin RST activates the LOCKED signal deactivates within four source clock cycles. The RST pin, active High, must either connect to a dynamic signal or tied to

Initialization in Verilog and Synopsys

The block SelectRAM+ structures can be initialized in Verilog for both simulation and synthesis for inclusion in the EDIF output file. The simulation of the Verilog code uses a defparam to pass the initialization. The Synopsys FPGA compiler does not presently support defparam. The initialization values instead attach as attributes to the RAM by a built-in Synopsys dc_script. The translate_off statement stops synthesis translation of the defparam statements. The following code illustrates a module that employs these techniques.

Design Examples

Creating a 32-bit Single-Port RAM

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single port, 128 deep by 32-bit wide RAM to be created using a single block SelectRAM+ cell as shown in **Figure 35**.

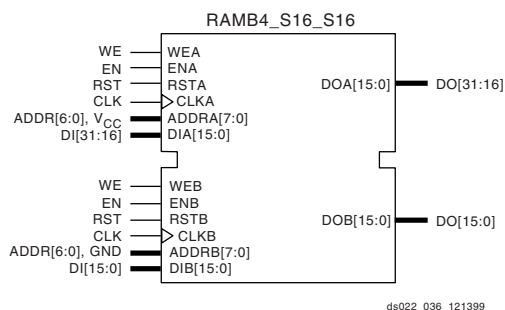


Figure 35: Single Port 128 x 32 RAM

Interleaving the memory space, setting the LSB of the address bus of Port A to 1 (V_{CC}), and the LSB of the

address bus of Port B to 0 (GND), allows a 32-bit wide single port RAM to be created.

Creating Two Single-Port RAMs

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single RAM to be split into two single port memories of 2K bits each as shown in **Figure 36**.

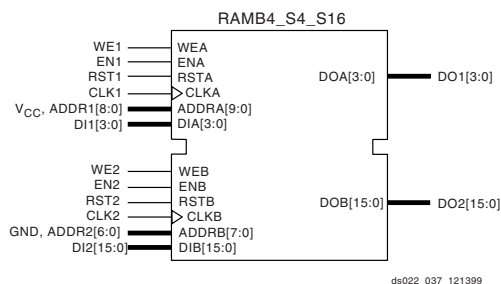


Figure 36: 512 x 4 RAM and 128 x 16 RAM

In this example, a 512K x 4 RAM (Port A) and a 128 x 16 RAM (Port B) are created out of a single block SelectRAM+. The address space for the RAM is split by fixing the MSB of Port A to 1 (V_{CC}) for the upper 2K bits and the MSB of Port B to 0 (GND) for the lower 2K bits.

Block Memory Generation

The CoreGen program generates memory structures using the block SelectRAM+ features. This program outputs VHDL or Verilog simulation code templates and an EDIF file for inclusion in a design.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUF placement restrictions require that any differential amplifier input signals within a bank be of the same standard. How to specify a specific location for the IBUF via the LOC property is described below. Table 19 summarizes the Virtex-E input standards compatibility requirements.

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element by default activates to ensure a zero hold-time requirement. The NODELAY=TRUE property overrides this default.

When the IBUF does not drive a flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

Table 19: Xilinx Input Standards Compatibility Requirements

Rule 1	Standards with the same input V_{CCO} , output V_{CCO} , and V_{REF} can be placed within the same bank.
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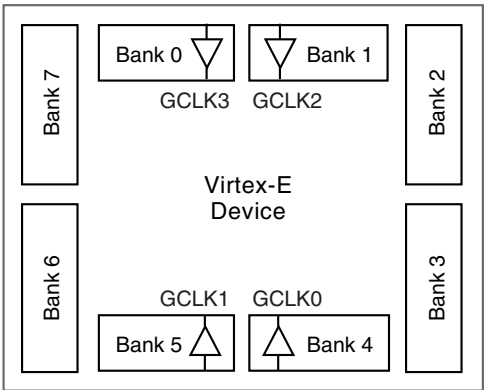


Figure 38: Virtex-E I/O Banks

IBUFG

Signals used as high fanout clock inputs to the Virtex-E device should drive a global clock input buffer (IBUFG) via an external input port in order to take advantage of one of the four dedicated global clock distribution networks. The output of the IBUFG should only drive a CLKDLL,

CLKDLLHF, or BUFG symbol. The generic Virtex-E IBUFG symbol appears in Figure 39.

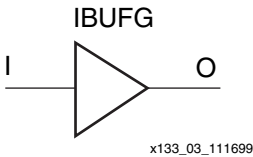


Figure 39: Virtex-E Global Clock Input Buffer (IBUFG) Symbol

The extension to the base name determines which I/O standard is used by the IBUFG. With no extension specified for the generic IBUFG symbol, the assumed standard is LVTTTL.

The following list details variations of the IBUFG symbol.

- IBUFG
- IBUFG_LVCMOS2
- IBUFG_PCI33_3
- IBUFG_PCI66_3
- IBUFG_GTL
- IBUFG_GTLP
- IBUFG_HSTL_I
- IBUFG_HSTL_III
- IBUFG_HSTL_IV
- IBUFG_SSTL3_I
- IBUFG_SSTL3_II
- IBUFG_SSTL2_I
- IBUFG_SSTL2_II
- IBUFG_CTT
- IBUFG_AGP
- IBUFG_LVCMOS18
- IBUFG_LVDS
- IBUFG_LVPECL

When the IBUFG symbol supports an I/O standard that requires a differential amplifier input, the IBUFG automatically configures as a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUFG placement restrictions require any differential amplifier input signals within a bank be of the same standard. The LOC property can specify a location for the IBUFG.

As an added convenience, the BUFGP can be used to instantiate a high fanout clock input. The BUFGP symbol

HSTL

A sample circuit illustrating a valid termination technique for HSTL_I appears in [Figure 46](#). A sample circuit illustrating a valid termination technique for HSTL_III appears in [Figure 47](#).

Table 25: HSTL Class I Voltage Specification

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	0.68	0.75	0.90
V_{TT}	-	$V_{CCO} \times 0.5$	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}			0.4
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

HSTL Class I

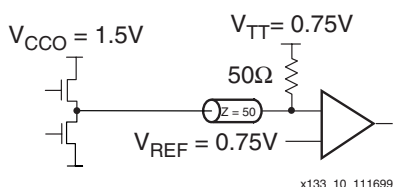


Figure 46: Terminated HSTL Class I

Table 26: HSTL Class III Voltage Specification

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
$V_{REF}^{(1)}$	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

HSTL Class III

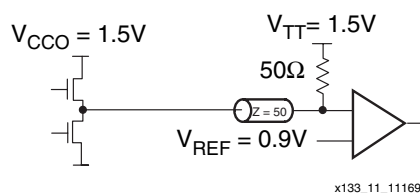


Figure 47: Terminated HSTL Class III

A sample circuit illustrating a valid termination technique for HSTL_IV appears in [Figure 48](#).

Table 27: HSTL Class IV Voltage Specification

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	48	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

HSTL Class IV

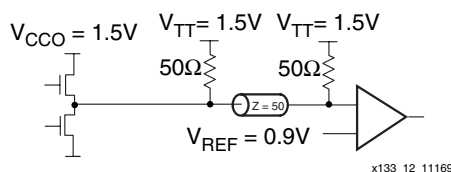


Figure 48: Terminated HSTL Class IV

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
CTT	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.4$	$V_{REF} + 0.4$	8	-8
AGP	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2

Notes:

1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.
3. DC input and output levels for HSTL18 (HSTL I/O standard with V_{CCO} of 1.8 V) are provided in an HSTL white paper on www.xilinx.com.

LVDS DC Specifications

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.375	2.5	2.625	V
Output High Voltage for Q and $\bar{Q}$	V_{OH}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	1.25	1.425	1.6	V
Output Low Voltage for Q and $\bar{Q}$	V_{OL}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	0.9	1.075	1.25	V
Differential Output Voltage (Q - $\bar{Q}$), Q = High ($\bar{Q}$ - Q), $\bar{Q}$ = High	V_{ODIFF}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	250	350	450	mV
Output Common-Mode Voltage	V_{OCM}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	1.125	1.25	1.375	V
Differential Input Voltage (Q - $\bar{Q}$), Q = High ($\bar{Q}$ - Q), $\bar{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25 V	100	350	NA	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ± 350 mV	0.2	1.25	2.2	V

Note: Refer to the Design Consideration section for termination schematics.

LVPECL DC Specifications

These values are valid at the output of the source termination pack shown under **LVPECL**, with a 100 Ω differential load only. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. The following table summarizes the DC output specifications of LVPECL.

DC Parameter	Min	Max	Min	Max	Min	Max	Units
V_{CCO}	3.0		3.3		3.6		V
V_{OH}	1.8	2.11	1.92	2.28	2.13	2.41	V
V_{OL}	0.96	1.27	1.06	1.43	1.30	1.57	V
V_{IH}	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential Input Voltage	0.3	-	0.3	-	0.3	-	V

CLB Arithmetic Switching Characteristics

Setup times not listed explicitly can be approximated by decreasing the combinatorial delays by the setup time adjustment listed. Precise values are provided by the timing analyzer.

		Speed Grade ⁽¹⁾				Units
Description	Symbol	Min	-8	-7	-6	
Combinatorial Delays						
F operand inputs to X via XOR	T _{OPX}	0.32	0.68	0.8	0.8	ns, max
F operand input to XB output	T _{OPXB}	0.35	0.65	0.8	0.9	ns, max
F operand input to Y via XOR	T _{OPY}	0.59	1.07	1.4	1.5	ns, max
F operand input to YB output	T _{OPYB}	0.48	0.89	1.1	1.3	ns, max
F operand input to COUT output	T _{OPCYF}	0.37	0.71	0.9	1.0	ns, max
G operand inputs to Y via XOR	T _{OPGY}	0.34	0.72	0.8	0.9	ns, max
G operand input to YB output	T _{OPGYB}	0.47	0.78	1.2	1.3	ns, max
G operand input to COUT output	T _{OPCYG}	0.36	0.60	0.9	1.0	ns, max
BX initialization input to COUT	T _{BXCY}	0.19	0.36	0.51	0.57	ns, max
CIN input to X output via XOR	T _{CINX}	0.27	0.50	0.6	0.7	ns, max
CIN input to XB	T _{CINXB}	0.02	0.04	0.07	0.08	ns, max
CIN input to Y via XOR	T _{CINY}	0.26	0.45	0.7	0.7	ns, max
CIN input to YB	T _{CINYB}	0.16	0.28	0.38	0.43	ns, max
CIN input to COUT output	T _{BYP}	0.05	0.10	0.14	0.15	ns, max
Multiplier Operation						
F1/2 operand inputs to XB output via AND	T _{FANDXB}	0.10	0.30	0.35	0.39	ns, max
F1/2 operand inputs to YB output via AND	T _{FANDYB}	0.28	0.56	0.7	0.8	ns, max
F1/2 operand inputs to COUT output via AND	T _{FANDCY}	0.17	0.38	0.46	0.51	ns, max
G1/2 operand inputs to YB output via AND	T _{GANDYB}	0.20	0.46	0.55	0.7	ns, max
G1/2 operand inputs to COUT output via AND	T _{GANDCY}	0.09	0.28	0.30	0.34	ns, max
Setup and Hold Times before/after Clock CLK						
CIN input to FFX	T _{CCKX} /T _{CKCX}	0.47 / 0	1.0 / 0	1.2 / 0	1.3 / 0	ns, min
CIN input to FFY	T _{CCKY} /T _{CKCY}	0.49 / 0	0.92 / 0	1.2 / 0	1.3 / 0	ns, min

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Table 4: CS144 — XCV50E, XCV100E, XCV200E

Bank	Pin Description	Pin #
1	VCCO	A13
1	VCCO	D7
2	VCCO	B12
3	VCCO	G11
3	VCCO	M13
4	VCCO	N13
5	VCCO	N1
5	VCCO	N7
6	VCCO	M2
7	VCCO	B2
7	VCCO	G2
NA	GND	A1
NA	GND	B9
NA	GND	B11
NA	GND	C7
NA	GND	D5
NA	GND	E4
NA	GND	E11
NA	GND	F1
NA	GND	G10
NA	GND	J1
NA	GND	J12
NA	GND	L3
NA	GND	L5
NA	GND	L7
NA	GND	L9
NA	GND	N12

Notes:

1. V_{REF} or I/O option only in the XCV200E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV100E, 200E; otherwise, I/O option only.

CS144 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A $\checkmark$ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 5: CS144 Differential Pin Pair Summary
XCV50E, XCV100E, XCV200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	K7	N8	NA	IO_DLL_L18P
1	5	M7	M6	NA	IO_DLL_L18N
2	1	A7	B7	NA	IO_DLL_L2P
3	0	A6	C6	NA	IO_DLL_L2N
IO LVDS					
Total Pairs: 30, Asynchronous Output Pairs: 18					
0	0	A4	B4	$\checkmark$	VREF
1	0	A5	B5	$\checkmark$	-
2	1	B7	C6	NA	IO_LVDS_DLL
3	1	D8	C8	$\checkmark$	-
4	1	D9	C9	$\checkmark$	VREF
5	1	D10	C10	$\checkmark$	CS, WRITE
6	2	C11	C12	$\checkmark$	DIN, D0
7	2	D13	E10	1	D1, VREF
8	2	E12	E13	$\checkmark$	D2
9	2	F10	F11	1	D3, VREF
10	3	F13	G13	NA	-
11	3	H12	H11	1	D4, VREF
12	3	H10	J13	$\checkmark$	D5
13	3	J11	J10	1	D6, VREF
14	3	K10	L13	$\checkmark$	INIT
15	4	L11	M11	$\checkmark$	-
16	4	N10	K9	$\checkmark$	VREF
17	4	N9	K8	$\checkmark$	-

HQ240 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A ✓ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

**Table 9: HQ240 Differential Pin Pair Summary
XCV600E, XCV1000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	P92	P93	NA	IO_DLL_L40P
1	5	P89	P87	NA	IO_DLL_L40N
2	1	P210	P209	NA	IO_DLL_L6P
3	0	P213	P215	NA	IO_DLL_L6N
IO LVDS					
Total Pairs: 64, Asynchronous Output Pairs: 53					
0	0	P236	P237	NA	VREF
1	0	P234	P235	✓	-
2	0	P228	P229	✓	VREF
3	0	P223	P224	✓	-
4	0	P220	P221	✓	-
5	0	P217	P218	✓	VREF
6	1	P209	P215	NA	IO_LVDS_DLL
7	1	P205	P206	✓	VREF
8	1	P202	P203	✓	-
9	1	P199	P200	✓	-
10	1	P194	P195	✓	VREF
11	1	P191	P192	✓	VREF
12	1	P188	P189	✓	-
13	1	P186	P187	NA	VREF
14	1	P184	P185	✓	CS
15	2	P178	P177	✓	DIN, D0

**Table 9: HQ240 Differential Pin Pair Summary
XCV600E, XCV1000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	2	P174	P173	✓	-
17	2	P171	P170	✓	VREF
18	2	P168	P167	✓	D1
19	2	P163	P162	✓	D2
20	2	P160	P159	✓	-
21	2	P157	P156	✓	D3
22	2	P155	P154	1	VREF
23	2	P153	P152	✓	-
24	3	P145	P144	✓	D4, VREF
25	3	P142	P141	✓	-
26	3	P139	P138	✓	D5
27	3	P134	P133	✓	VREF
28	3	P131	P130	✓	VREF
29	3	P128	P127	✓	-
30	3	P126	P125	1	VREF
31	3	P124	P123	✓	INIT
32	4	P118	P117	✓	-
33	4	P114	P113	✓	-
34	4	P111	P110	✓	VREF
35	4	P108	P107	✓	VREF
36	4	P103	P102	✓	-
37	4	P100	P99	✓	-
38	4	P97	P96	✓	VREF
39	4	P95	P94	NA	VREF
40	5	P93	P87	NA	IO_LVDS_DLL
41	5	P84	P82	NA	VREF
42	5	P79	P78	✓	-
43	5	P74	P73	✓	VREF
44	5	P71	P70	✓	VREF
45	5	P68	P67	✓	-
46	5	P66	P65	NA	VREF
47	5	P64	P63	✓	-

Table 10: BG352 — XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
0	IO	C15
0	IO	B15 ¹
0	IO_LVDS_DLL_L9N	A15
0	GCK3	D14
1	GCK2	B14
1	IO_LVDS_DLL_L9P	A13
1	IO	B13 ¹
1	IO_L10N	C13
1	IO_L10P	A12
1	IO_L11N_Y	B12
1	IO_VREF_1_L11P_Y	C12
1	IO_L12N_Y	A11
1	IO_L12P_Y	B11
1	IO	B10 ¹
1	IO_L13N	C11
1	IO_L13P	D11
1	IO	A9 ¹
1	IO_L14N_YY	B9
1	IO_L14P_YY	C10
1	IO_L15N_YY	B8
1	IO_VREF_1_L15P_YY	C9
1	IO_L16N_Y	D9
1	IO_L16P_Y	A7
1	IO	B7
1	IO	C8 ¹
1	IO	D8 ¹
1	IO_L17N_YY	A6
1	IO_VREF_1_L17P_YY	B6
1	IO_L18N_YY	C7
1	IO_L18P_YY	A4
1	IO	B5 ¹
1	IO_L19N_YY	C6
1	IO_VREF_1_L19P_YY	D6 ²

Table 10: BG352 — XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
1	IO	B4
1	IO	C5 ¹
1	IO	A3 ¹
1	IO_WRITE_L20N_YY	D5
1	IO_CS_L20P_YY	C4
2	IO_DOUT_BUSY_L21P_YY	E4
2	IO_DIN_D0_L21N_YY	D3
2	IO	C2 ¹
2	IO	E3 ¹
2	IO	F4
2	IO_VREF_2_L22P_YY	D2 ²
2	IO_L22N_YY	C1
2	IO	D1 ¹
2	IO_L23P_YY	G4
2	IO_L23N_YY	F3
2	IO_VREF_2_L24P_Y	E2
2	IO_L24N_Y	F2
2	IO	G3 ¹
2	IO	G2 ¹
2	IO_L25P	F1
2	IO_L25N	J4
2	IO	H3
2	IO_VREF_2_L26P_Y	H2
2	IO_D1_L26N_Y	G1
2	IO_D2_L27P_YY	J3
2	IO_L27N_YY	J2
2	IO	K3 ¹
2	IO_L28P	J1
2	IO_L28N	L4
2	IO	K2 ¹
2	IO_L29P_YY	L3
2	IO_L29N_YY	L2
2	IO_VREF_2_L30P_Y	M4

Table 10: BG352 — XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
2	IO_D3_L30N_Y	M3
2	IO_L31P	M2
2	IO_L31N	M1
2	IO	N3 ¹
2	IO_L32P_YY	N4
2	IO_L32N_YY	N2
3	IO	P1
3	IO	P3 ¹
3	IO_L33P	R1
3	IO_L33N	R2
3	IO_D4_L34P_Y	R3
3	IO_VREF_3_L34N_Y	R4
3	IO_L35P_YY	T2
3	IO_L35N_YY	U2
3	IO	T3 ¹
3	IO_L36P	T4
3	IO_L36N	V1
3	IO	V2 ¹
3	IO_L37P_YY	U3
3	IO_D5_L37N_YY	U4
3	IO_D6_L38P_Y	V3
3	IO_VREF_3_L38N_Y	V4
3	IO_L39P_Y	Y1
3	IO_L39N_Y	Y2
3	IO	W3
3	IO	W4 ¹
3	IO	AA1 ¹
3	IO_L40P_Y	AA2
3	IO_VREF_3_L40N_Y	Y3
3	IO_L41P_YY	AC1
3	IO_L41N_YY	AB2
3	IO	AA3 ¹
3	IO_L42P_YY	AA4

Table 10: BG352 — XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
3	IO_VREF_3_L42N_YY	AC2 ²
3	IO	AB3
3	IO	AD1 ¹
3	IO	AB4 ¹
3	IO_D7_L43P_YY	AC3
3	IO_INIT_L43N_YY	AD2
4	IO_L44P_YY	AC5
4	IO_L44N_YY	AD4
4	IO	AE3 ¹
4	IO	AD5 ¹
4	IO	AC6
4	IO_VREF_4_L45P_YY	AE4 ²
4	IO_L45N_YY	AF3
4	IO	AF4 ¹
4	IO_L46P_YY	AC7
4	IO_L46N_YY	AD6
4	IO_VREF_4_L47P_YY	AE5
4	IO_L47N_YY	AE6
4	IO	AD7 ¹
4	IO	AE7 ¹
4	IO_L48P	AF6
4	IO_L48N	AC9
4	IO	AD8
4	IO_VREF_4_L49P_YY	AE8
4	IO_L49N_YY	AF7
4	IO_L50P_YY	AD9
4	IO_L50N_YY	AE9
4	IO	AD10 ¹
4	IO_L51P	AF9
4	IO_L51N	AC11
4	IO	AE10 ¹
4	IO_L52P_Y	AD11
4	IO_L52N_Y	AE11

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
NA	VCCINT	N29	
NA	VCCINT	N33	
NA	VCCINT	U5	
NA	VCCINT	U30	
NA	VCCINT	Y2	
NA	VCCINT	Y31	
NA	VCCINT	AB2	
NA	VCCINT	AB32	
NA	VCCINT	AD2	
NA	VCCINT	AD32	
NA	VCCINT	AG3	
NA	VCCINT	AG31	
NA	VCCINT	AJ13	
NA	VCCINT	AK8	
NA	VCCINT	AK11	
NA	VCCINT	AK17	
NA	VCCINT	AK20	
NA	VCCINT	AL14	
NA	VCCINT	AL22	
NA	VCCINT	AL27	
NA	VCCINT	AN25	
0	VCCO	A22	
0	VCCO	A26	
0	VCCO	A30	
0	VCCO	B19	
0	VCCO	B32	
1	VCCO	A10	
1	VCCO	A16	
1	VCCO	B13	
1	VCCO	C3	
1	VCCO	E5	
2	VCCO	B2	
2	VCCO	D1	
2	VCCO	H1	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
2	VCCO	M1	
2	VCCO	R2	
3	VCCO	V1	
3	VCCO	AA2	
3	VCCO	AD1	
3	VCCO	AK1	
3	VCCO	AL2	
4	VCCO	AN4	
4	VCCO	AN8	
4	VCCO	AN12	
4	VCCO	AM2	
4	VCCO	AM15	
5	VCCO	AL31	
5	VCCO	AM21	
5	VCCO	AN18	
5	VCCO	AN24	
5	VCCO	AN30	
6	VCCO	W32	
6	VCCO	AB33	
6	VCCO	AF33	
6	VCCO	AK33	
6	VCCO	AM32	
7	VCCO	C32	
7	VCCO	D33	
7	VCCO	K33	
7	VCCO	N32	
7	VCCO	T33	
NA	GND	A1	
NA	GND	A7	
NA	GND	A12	
NA	GND	A14	
NA	GND	A18	
NA	GND	A20	
NA	GND	A24	

Table 19: FG456 Differential Pin Pair Summary
XCV200E, XCV300E

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	1	C14	B14	2	-
19	1	A15	F12	2	-
20	1	C15	B15	√	-
21	1	E14	A16	√	VREF
22	1	C16	D14	2	-
23	1	A17	D15	2	-
24	1	A18	B17	√	VREF
25	1	C17	D16	√	-
26	1	A19	B18	√	VREF
27	1	C18	D17	√	-
28	1	C19	A20	√	CS
29	2	C21	D20	√	DIN, D0
30	2	C22	D21	√	-
31	2	D22	E21	√	VREF
32	2	E22	F18	√	-
33	2	F21	F19	√	VREF
34	2	F22	G19	2	-
35	2	G20	G18	1	-
36	2	H18	H22	2	D1, VREF
37	2	H20	H19	√	D2
38	2	H21	J19	√	-
39	2	J18	J20	√	-
40	2	K18	J21	2	-
41	2	K22	K21	1	VREF
42	2	K19	L22	2	-
43	2	L21	L18	√	-
44	2	L17	L20	√	-
45	3	M18	M20	√	-
46	3	M19	M17	2	-
47	3	N22	N21	2	VREF
48	3	N20	N18	√	-
49	3	N19	P21	√	-
50	3	P20	P19	√	-
51	3	P18	R21	√	D5
52	3	T22	R19	2	VREF

Table 19: FG456 Differential Pin Pair Summary
XCV200E, XCV300E

Pair	Bank	P Pin	N Pin	AO	Other Functions
53	3	U22	R18	2	-
54	3	T21	V22	√	-
55	3	T20	U21	√	VREF
56	3	W22	T18	√	-
57	3	U19	U20	√	VREF
58	3	W21	AA22	√	-
59	3	Y21	V19	√	INIT
60	4	W18	AA20	√	-
61	4	Y18	V17	NA	-
62	4	AB20	W17	√	VREF
63	4	AA18	V16	NA	-
64	4	AB19	AB18	√	VREF
65	4	W16	AA17	1	-
66	4	Y16	V15	1	-
67	4	AB16	Y15	√	VREF
68	4	AA15	AB15	√	-
69	4	W15	Y14	1	-
70	4	V14	AA14	1	-
71	4	AB14	V13	NA	-
72	4	AA13	AB13	√	VREF
73	4	W13	AA12	2	-
74	4	Y12	V12	2	-
75	5	U12	AA11	NA	IO_LVDS_DLL
76	5	AB11	W11	1	-
77	5	V11	Y10	√	VREF
78	5	AB10	W10	√	-
79	5	V10	Y9	2	-
80	5	AB9	W9	2	-
81	5	V9	AA8	√	-
82	5	Y8	W8	√	VREF
83	5	W7	AA7	2	-
84	5	AB6	AA6	2	-
85	5	AB5	AA5	√	VREF
86	5	Y7	W6	√	-
87	5	AA4	Y6	√	VREF

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
5	IO_L129N_Y	AB9
5	IO_L130P_YY	AA9
5	IO_L130N_YY	AF6
5	IO_L131P_YY	AC8
5	IO_VREF_L131N_YY	AC7
5	IO_L132P_YY	AD6
5	IO_L132N_YY	Y9
5	IO_L133P_YY	AE5
5	IO_L133N_YY	AA8
5	IO_L134P_YY	AC6
5	IO_VREF_L134N_YY	AB8
5	IO_L135P_YY	AD5
5	IO_L135N_YY	AA7
5	IO_L136P_Y	AF4
5	IO_L136N_Y	AC5
6	IO	P3
6	IO	AA3
6	IO	AC1 ¹
6	IO	P1 ¹
6	IO	R2 ¹
6	IO	T1 ¹
6	IO	V1 ¹
6	IO	W3
6	IO	Y2
6	IO	Y6
6	IO_L137N_YY	AA5
6	IO_L137P_YY	AC3
6	IO_L138N_YY	AC2
6	IO_L138P_YY	AB4
6	IO_L139N_Y	W6
6	IO_L139P_Y	AA4
6	IO_VREF_L140N_Y	AB3
6	IO_L140P_Y	Y5
6	IO_L141N_Y	AB2
6	IO_L141P_Y	V7
6	IO_L142N_YY	AB1

Table 20: FG676 — XCV400E, XCV600E

Bank	Pin Description	Pin #
6	IO_L142P_YY	Y4
6	IO_VREF_L143N_YY	V5
6	IO_L143P_YY	W5
6	IO_L144N_YY	AA1
6	IO_L144P_YY	V6
6	IO_L145N_Y	W4
6	IO_L145P_Y	Y3
6	IO_VREF_L146N_Y	Y1 ²
6	IO_L146P_Y	U7
6	IO_L147N_YY	W1
6	IO_L147P_YY	V4
6	IO_L148N_YY	W2
6	IO_VREF_L148P_YY	U6
6	IO_L149N_YY	V3
6	IO_L149P_YY	T5
6	IO_L150N_YY	U5
6	IO_L150P_YY	U4
6	IO_L151N_Y	T7
6	IO_L151P_Y	U3
6	IO_L152N_Y	U2
6	IO_L152P_Y	T6
6	IO_L153N_Y	U1
6	IO_L153P_Y	T4
6	IO_L154N_Y	R7
6	IO_L154P_Y	T3
6	IO_VREF_L155N_YY	R4
6	IO_L155P_YY	R6
6	IO_L156N_YY	R3
6	IO_L156P_YY	R5
6	IO_L157N_Y	P8
6	IO_L157P_Y	P7
6	IO_VREF_L158N_Y	R1
6	IO_L158P_Y	P6
6	IO_L159N_YY	P5
6	IO_L159P_YY	P4
7	IO	D1 ¹

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
3	IO_L117N_Y	AJ5
3	IO_L118P	AG2
3	IO_L118N	AK4
3	IO_L119P_Y	AG3
3	IO_L119N_Y	AL4
3	IO_L120P_Y	AH1
3	IO_L120N_Y	AL5
3	IO_L121P_Y	AH2
3	IO_L121N_Y	AM4
3	IO_L122P_YY	AH3
3	IO_D5_L122N_YY	AM5
3	IO_D6_L123P_YY	AJ1
3	IO_VREF_L123N_YY	AN3
3	IO_L124P_Y	AN4
3	IO_L124N_Y	AJ3
3	IO_L125P_YY	AN5
3	IO_L125N_YY	AK1
3	IO_L126P_YY	AK2
3	IO_VREF_L126N_YY	AP4
3	IO_L127P_Y	AK3
3	IO_L127N_Y	AP5
3	IO_L128P_Y	AR3
3	IO_VREF_L128N_Y	AL2 ²
3	IO_L129P_YY	AR4
3	IO_L129N_YY	AL3
3	IO_L130P_YY	AM1
3	IO_VREF_L130N_YY	AT3
3	IO_L131P_Y	AM2
3	IO_L131N_Y	AT4
3	IO_L132P_Y	AT5
3	IO_L132N_Y	AN1
3	IO_L133P_YY	AU3
3	IO_L133N_YY	AN2
3	IO_L134P_Y	AP1
3	IO_VREF_L134N_Y	AP2
3	IO_L135P_Y	AR1
3	IO_L135N_Y	AV3

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
3	IO_L136P	AR2
3	IO_L136N	AT1
3	IO_L137P_Y	AV4
3	IO_VREF_L137N_Y	AT2
3	IO_L138P_Y	AU1
3	IO_L138N_Y	AU5
3	IO_L139P_Y	AU2
3	IO_L139N_Y	AW3
3	IO_D7_L140P_YY	AV1
3	IO_INIT_L140N_YY	AW5
4	GCK0	BA22
4	IO	AV17
4	IO	AY11
4	IO	AY12
4	IO	AY13
4	IO	AY14
4	IO	BA8
4	IO	BA17
4	IO	BA19
4	IO	BA20
4	IO	BA21
4	IO	BB9
4	IO	BB18
4	IO_L141P_YY	AV6
4	IO_L141N_YY	BA4
4	IO_L142P_Y	AY4
4	IO_L142N_Y	BA5
4	IO_L143P_Y	AW6
4	IO_L143N_Y	BB5
4	IO_VREF_L144P_Y	BA6
4	IO_L144N_Y	AY5
4	IO_L145P_Y	BB6
4	IO_L145N_Y	AY6
4	IO_L146P_YY	BA7
4	IO_L146N_YY	AV7
4	IO_VREF_L147P_YY	BB7

Table 27: FG900 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
256	7	N6	M6	1	-
257	7	N1	N5	4	-
258	7	M5	M4	√	-
259	7	M1	M2	1	VREF
260	7	L2	L4	4	-
261	7	L5	M7	3	-
262	7	M8	L1	4	-
263	7	M9	K2	1	-
264	7	M10	L3	NA	-
265	7	K1	K5	√	-
266	7	K3	L6	√	VREF
267	7	K4	L7	4	-
268	7	J5	L8	4	-
269	7	H4	K6	4	VREF
270	7	K7	H1	4	-
271	7	J2	J7	2	-
272	7	G2	H5	√	-
273	7	G5	L9	√	VREF
274	7	K8	F3	1	-
275	7	E1	G3	4	-
276	7	E2	H6	√	-
277	7	K9	E4	1	VREF
278	7	F4	J8	4	-
279	7	H7	D1	3	-
280	7	C2	G6	4	VREF
281	7	F5	D2	1	-
282	7	K10	D3	4	-

Notes:

1. AO in the XCV600E, 1000E.
2. AO in the XCV1000E.
3. AO in the XCV1600E.
4. AO in the XCV1000E, XCV1600E.

FG1156 Fine-Pitch Ball Grid Array Package

XCV1000E, XCV1600E, XCV2000E, XCV2600E, and XCV3200E devices in the FG1156 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled IO_VREF can be used as either V_{REF} or general I/O, unless indicated in the footnotes. If the pin is not used as V_{REF} , it can be used as general I/O. Immediately following Table 28, see Table 29 for Differential Pair information.

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
0	GCK3	E17
0	IO	B4
0	IO	B9
0	IO	B10
0	IO	D9 ³
0	IO	D16
0	IO	E7 ³
0	IO	E11 ³
0	IO	E13 ³
0	IO	E16 ³
0	IO	F17 ³
0	IO	J12 ³
0	IO	J13 ³
0	IO	J14 ³
0	IO	K11 ³
0	IO_L0N_Y	F7
0	IO_L0P_Y	H9
0	IO_L1N_Y	C5
0	IO_L1P_Y	J10
0	IO_VREF_L2N_Y	E6
0	IO_L2P_Y	D6
0	IO_L3N_Y	A4
0	IO_L3P_Y	G8
0	IO_L4N_YY	C6
0	IO_L4P_YY	J11
0	IO_VREF_L5N_YY	G9
0	IO_L5P_YY	F8
0	IO_L6N_YY	A5 ⁴

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCO_2	T23
NA	VCCO_2	T24
NA	VCCO_2	R23
NA	VCCO_2	R24
NA	VCCO_2	P23
NA	VCCO_2	P24
NA	VCCO_2	P32
NA	VCCO_2	N23
NA	VCCO_3	V23
NA	VCCO_3	V24
NA	VCCO_3	Y23
NA	VCCO_3	Y24
NA	VCCO_3	W23
NA	VCCO_3	W24
NA	VCCO_3	AJ34
NA	VCCO_3	AE30
NA	VCCO_3	AC24
NA	VCCO_3	AB23
NA	VCCO_3	AB24
NA	VCCO_3	AA23
NA	VCCO_3	AA24
NA	VCCO_3	AA32
NA	VCCO_4	AD18
NA	VCCO_4	AC18
NA	VCCO_4	AC19
NA	VCCO_4	AC20
NA	VCCO_4	AC21
NA	VCCO_4	AC22
NA	VCCO_4	AP29
NA	VCCO_4	AM21
NA	VCCO_4	AK25
NA	VCCO_4	AD19
NA	VCCO_4	AD20
NA	VCCO_4	AD21

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCO_4	AD22
NA	VCCO_4	AD23
NA	VCCO_5	AC17
NA	VCCO_5	AD17
NA	VCCO_5	AC13
NA	VCCO_5	AC14
NA	VCCO_5	AC15
NA	VCCO_5	AC16
NA	VCCO_5	AP6
NA	VCCO_5	AM14
NA	VCCO_5	AK10
NA	VCCO_5	AD12
NA	VCCO_5	AD13
NA	VCCO_5	AD14
NA	VCCO_5	AD15
NA	VCCO_5	AD16
NA	VCCO_6	V11
NA	VCCO_6	V12
NA	VCCO_6	Y11
NA	VCCO_6	Y12
NA	VCCO_6	W11
NA	VCCO_6	W12
NA	VCCO_6	AJ1
NA	VCCO_6	AE5
NA	VCCO_6	AC11
NA	VCCO_6	AB11
NA	VCCO_6	AB12
NA	VCCO_6	AA3
NA	VCCO_6	AA11
NA	VCCO_6	AA12
NA	VCCO_7	U11
NA	VCCO_7	U12
NA	VCCO_7	N12
NA	VCCO_7	M11

Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
270	6	AG2	AE7	2600 2000 1000	-
271	6	AG1	AF6	3200 2600 2000 1600 1000	VREF
272	6	AG4	AC9	2000 1600	-
273	6	AF3	AE6	3200 2600 2000 1600 1000	-
274	6	AF4	AF1	2600 1000	VREF
275	6	AF2	AB10	3200 2600 1600	-
276	6	AE1	AC8	3200 2600 1600 1000	-
277	6	AE3	AD5	3200 2600 2000 1600 1000	VREF
278	6	AD1	AC7	3200 2600 2000 1600 1000	-
279	6	AD2	AD6	3200 1600 1000	-
280	6	AC1	AB8	2000 1600 1000	VREF
281	6	AC2	AC5	3200 2600 2000 1600 1000	-
282	6	AC3	AA9	3200 2600 2000	-
283	6	AD4	AC4	2000 1000	-
284	6	AB6	AA8	3200 2600 1600 1000	-
285	6	Y10	AB1	2600 1600	-
286	6	AA7	AB2	3200 1600 1000	-
287	6	AA1	AA4	2600 2000 1000	VREF
288	6	AB4	Y9	3200 2600 2000 1600	-
289	6	Y8	AA2	3200 2600 2000 1600 1000	-

Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
290	6	AA5	AA6	3200 2600 1600 1000	-
291	6	Y7	AB3	3200 2600 2000	-
292	6	W10	Y1	2600 2000 1000	-
293	6	Y2	Y5	2000 1600 1000	VREF
294	6	W2	W9	2000 1600	-
295	6	Y4	W7	3200 2600 2000 1600 1000	-
296	6	Y6	W1	1000	-
297	6	W3	W6	3200 1600	-
298	6	W4	V9	3200 2600 1600 1000	-
299	6	V1	W5	2000 1600 1000	VREF
300	6	U2	V7	2000 1600 1000	-
301	6	U1	V6	3200 2600 1600 1000	VREF
302	7	U4	U9	3200 2600 2000 1600 1000	-
303	7	U5	U7	3200 2600 1600 1000	VREF
304	7	U6	U3	2000 1600 1000	-
305	7	T6	T3	2000 1600 1000	VREF
306	7	T4	T9	3200 2600 1600 1000	-
307	7	R1	T5	3200 1600	-
308	7	T10	R6	1000	-
309	7	R5	R2	3200 2600 2000 1600 1000	-
310	7	P5	P1	2000 1600 1000	VREF